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MEMS audio sensor high-performance analog bottom-port microphone

Datasheet - production data



Features

- Single supply voltage operation
- Low power consumption
- Omnidirectional sensitivity
- High signal-to-noise ratio
- · High bandwidth
- · Package compliant with reflow soldering

Description

The MP23AB02B is a compact, low-power microphone built with a low-profile sensing element.

The sensing element, capable of detecting acoustic waves, is manufactured using a specialized silicon micromachining process to produce audio sensors.

The MP23AB02B has an acoustic overload point of 125 dBSPL with a 64 dB signal-to-noise ratio.

The MP23AB02B is available in a package compliant with reflow soldering and is guaranteed to operate over an extended temperature range from -40 °C to +85 °C.

Table 1. Device summary

Order code	Temperature range (°C)	Package	Packing
MP23AB02B	-40 to +85	(3.35 x 2.5 x 0.98) mm	Tray
MP23AB02BTR	-40 to +85	(3.35 x 2.5 x 0.98) mm	Tape and reel

Pin description MP23AB02B

1 Pin description

Figure 1. Pin connections

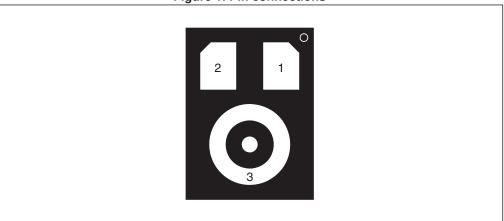


Table 2. Pin description

Pin n°	Pin name	Function
1	Out	Analog output
2	Vdd	Power supply
3	GND	Ground

2 Acoustic and electrical specifications

2.1 Acoustic and electrical characteristics

The values listed in the table below are specified for Vdd = 1.8 V, T_{amb} = 25 °C unless otherwise specified.

Table 3. Acoustic and electrical characteristics

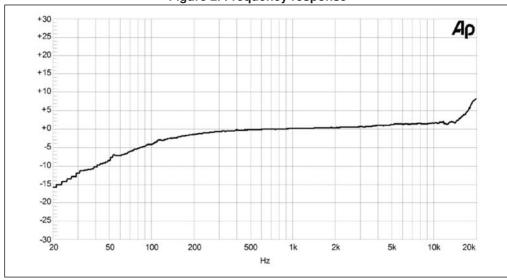
Symbol	Parameter	Test condition	Min.	Typ. ⁽¹⁾	Max.	Unit
Vdd	Supply voltage		1.6	1.8	3.6	V
ldd	Current consumption	mean value = 2 V		150	220	μA
So	Sensitivity	1 kHz (0 dB = 1 V/Pa)	-41	-38	-35	dBV/PA
SNR	Signal-to-noise ratio	A-weighted, 1 kHz (0 dB = 1 V/Pa)		64		dBA
Тор	Operating temperature range		-40		+85	°C

^{1.} Typical specifications are not guaranteed

Table 4. Distortion specifications at 1 kHz

Parameter	Test condition	Value
Distortion	94	< 0.5%
Distortion	120	< 2%
Distortion	124	= 10%

Figure 2. Frequency response



Absolute maximum ratings 3

Stresses above those listed as "Absolute maximum ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device under these conditions is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Table 5. Absolute maximum ratings

Symbol	Ratings	Maximum value	Unit
Vdd	Supply voltage	-0.5 to 4	V
T _{STG}	Storage temperature range	-40 to +125	°C



This device is sensitive to mechanical shock, improper handling can cause permanent damage to the part.

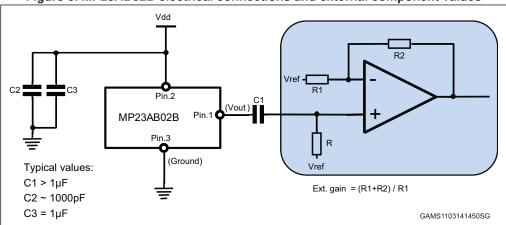


This device is sensitive to electrostatic discharge (ESD), improper handling can cause permanent damage to the part.



4 Application recommendations

Figure 3. MP23AB02B electrical connections and external component values



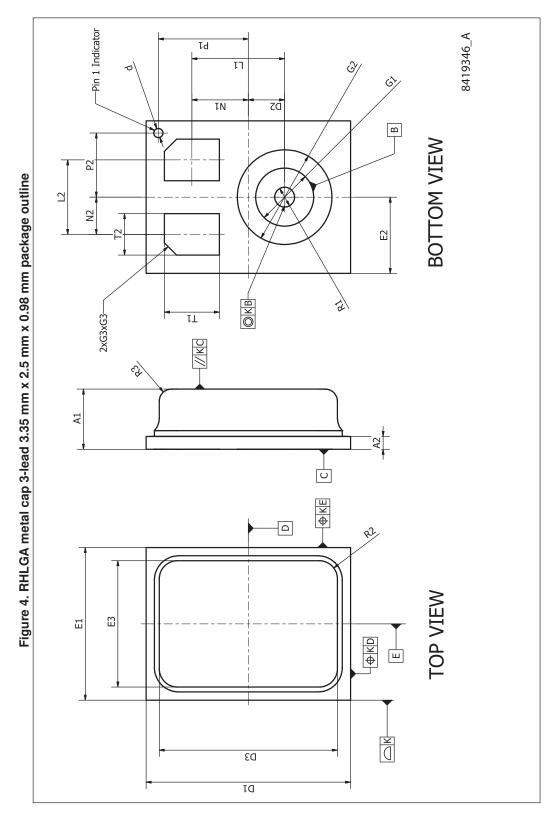


5 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK $^{\oplus}$ packages, depending on their level of environmental compliance. ECOPACK $^{\oplus}$ specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK $^{\oplus}$ is an ST trademark.



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Table 6. RHLGA metal cap 3-lead (3.35 x 2.5 x 0.98 mm9 package dimensions

Deference	Dimensions (mm)			
Reference	Min.	Тур.	Max.	
A1	0.880	0.980	1.080	
A2	0.200	0.250	0.300	
D1	3.250	3.350	3.450	
D2	0.495	0.595	0.695	
D3	2.770	2.920	3.070	
R1	0.275	0.325	0.375	
R2		0.28		
R3		0.25		
E1	2.400	2.500	2.600	
E2	1.150	1.250	1.350	
E3	1.920	2.070	2.220	
L1	1.480	1.520	1.560	
L2	1.180	1.220	1.260	
N1	0.885	0.925	0.965	
N2	0.570	0.610	0.650	
T1	0.860	0.900	0.940	
T2	0.640	0.680	0.720	
G1	0.900	0.950	1.000	
G2	1.400	1.550	1.600	
G3	0.100	0.150	0.200	
P1	1.425	1.475	1.525	
P2	1.000	1.050	1.100	
d		0.150		
К		0.050		

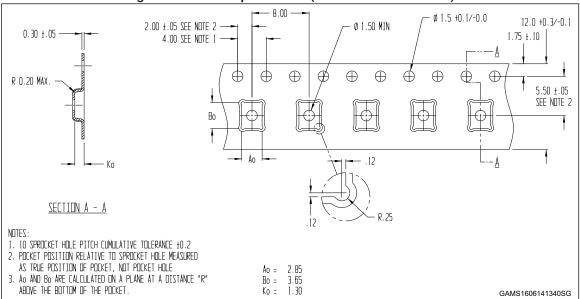


Figure 5. RHLGA tape and reel (dimensions are in mm.)



6 Soldering information

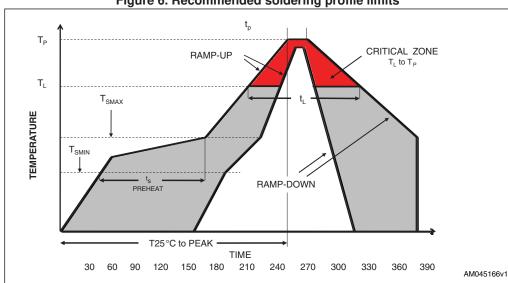


Figure 6. Recommended soldering profile limits

Table 7. Recommended soldering profile limits

Description	Parameter	Pb free	
Average ramp rate	T_L to T_P	3 °C/sec max	
Preheat			
Minimum temperature Maximum temperature Time (T _{SMIN} to T _{SMAX})	T _{SMIN} T _{SMAX} t _S	150 °C 200 °C 60 sec to 120 sec	
Ramp-up rate	T _{SMAX} to T _L		
Time maintained above liquidus temperature Liquidus temperature	t _L T _L	60 sec to 150 sec 217 °C	
Peak temperature	T _P	260 °C max	
Time within 5 °C of actual peak temperature		20 sec to 40 sec	
Ramp-down rate		6 °C/sec max	
Time 25 °C (t = 25 °C) to peak temperature		8 minutes max	



MP23AB02B Revision history

7 Revision history

Table 8. Document revision history

Date	Revision	Changes
21-Mar-2014	1	Initial release.
16-Jun-2014	2	Updated Figure 5 on page 9.
22-Sep-2014	3	Updated acoustic overload point in Description.

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